

SHENZHEN SUDING TECHNOLOGY.,CO LTD

Add: Room 401,402,403,Building D,Huafeng International Robot Industrial Park,Intersection of Baoan Avenue and Hangcheng Avenue, Baoan District, Shenzhen China

Date: 2024-3-16

FCC ID: 2BD3L-DGSD112

Dear Sir/Madam,

We, **SHENZHEN SUDING TECHNOLOGY.,CO LTD** Hereby declares the following statement for Federal Communications Commission, PCB board, circuit, structure and internal of these model(s) are the same, The different info for these model reference the blue text:

Product name: CAR DONGLE

Model no.: DGSD112, DGSD122, DGSD132, DGSD142, DGSD152, DGSD162, DGSD172, DGSD182, DGSD192

DGSD112: IPC image processing chip V851SE with USB port (white case)

DGSD122: IPC image processing chip V851SE, welded wire (welded wire)

DGSD132: IPC image processing chip V851SE, USB port welded down (black case)

DGSD142: IPC image processing chip V839 with USB port (white case)

DGSD152, IPC image processing chip V839, welding wire (welding wire)

DGSD162: IPC image processing chip V839, USB port welding position sinking (black case)

DGSD172: IPC image processing chip V851S with USB port (white case)

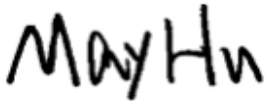
DGSD182: IPC image processing chip V851S, welded wire (welded wire)

DGSD192: IPC image processing chip V851S, USB port welded down (black case model)

Model difference: Different shell appearance and color

Among them: the motherboards of different chips are respectively tested for EMC (in fact, V839 is V851SE, but the screen printing model is changed)

Sincerely,



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